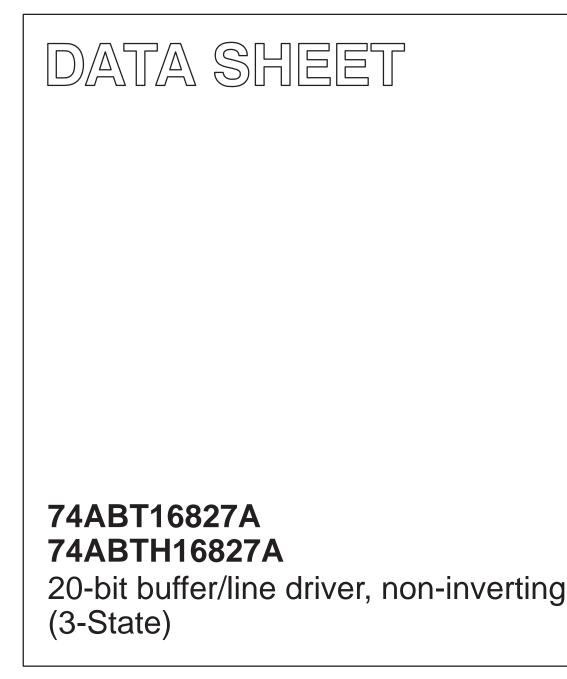
INTEGRATED CIRCUITS



Product specification Supersedes data of 1995 Aug 31 IC23 Data Handbook 1998 Feb 27



74ABT16827A 74ABTH16827A

FEATURES

- Multiple V_{CC} and GND pins minimize switching noise
- Live insertion/extraction permitted
- 3-State output buffers
- Power-up 3-State
- 74ABTH16827A incorporates bus-hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- Output capability: +64mA/-32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model

DESCRIPTION

The 74ABT16827A high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT16827A 20-bit buffers provide high performance bus interface buffering for wide data/address paths or buses carrying parity. They have NOR Output Enables (n $\overline{OE1}$, n $\overline{OE2}$) for maximum control flexibility.

Two options are available, 74ABT16827A which does not have the bus-hold feature and 74ABTH16827A which incorporates the bus-hold feature.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	$C_L = 50 pF; V_{CC} = 5V$	1.7 1.4	ns
C _{IN}	Input capacitance	$V_I = 0V \text{ or } V_{CC}$	4	pF
C _{OUT}	Output capacitance	$V_{O} = 0V$ or V_{CC} ; 3-State	6	pF
Iccz	Quiescent supply current	Outputs disabled; $V_{CC} = 5.5V$	500	μΑ
I _{CCL}		Outputs Low; $V_{CC} = 5.5V$	9	mA

ORDERING INFORMATION

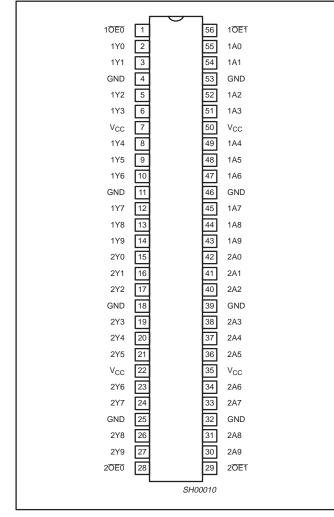
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type III	–40°C to +85°C	74ABT16827A DL	BT16827A DL	SOT371-1
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABT16827A DGG	BT16827A DGG	SOT364-1
56-Pin Plastic SSOP Type III	–40°C to +85°C	74ABTH16827A DL	BH16827A DL	SOT371-1
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABTH16827A DGG	BH16827A DGG	SOT364-1

PIN DESCRIPTION

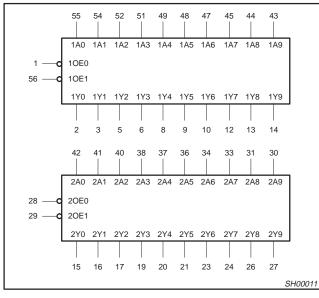
PIN NUMBER	SYMBOL	FUNCTION
55, 54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31, 30	1A0 - 1A9 2A0 - 2A9	Data inputs
2, 3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26, 27	1Y0 - 1Y9 2Y0 - 2Y9	Data outputs
1, 56, 28, 29	10E0, 10E1 20E0, 20E1	Output enable inputs (active-Low)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0V)
7, 22, 35, 50	V _{CC}	Positive supply voltage

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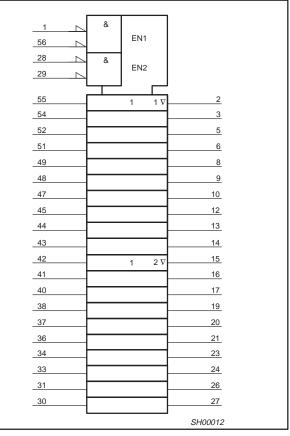
PIN CONFIGURATION



LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INPL	JTS	OUTPUTS	OPERATING MODE
nOEx	nAx	nYx	
L	L	L	Transparent
L	Н	Н	Transparent
Н	Х	Z	High impedance

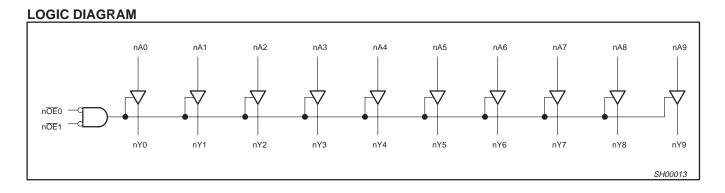
X = Don't care

Z = High impedance "off" state

H = High voltage level

L = Low voltage level

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ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{ОК}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	Output in Off or High state	-0.5 to +5.5	V
		Output in Low state	128	mA
lout	DC output current	Output in High state	-64	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

3.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
STWBOL	PARAMETER	MIN	MAX	UNIT
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level Input voltage		0.8	V
I _{ОН}	High-level output current		-32	mA
I _{OL}	Low-level output current		64	mA
Δt/Δv	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

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DC ELECTRICAL CHARACTERISTICS

				LIMITS					
SYMBOL	PARAMETER	TEST CONDITIONS		T _{amb} = +25°C			T _{amb} = -40°C to +85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	1
V _{IK}	Input clamp voltage	V _{CC} = 4.5V; I _{IK} = -18mA			-0.9	-1.2		-1.2	V
		V _{CC} = 4.5V; I _{OH} = -3mA; V _I = V	_{IL} or V _{IH}	2.5	2.9		2.5		V
V _{OH}	High-level output voltage	V _{CC} = 5.0V; I _{OH} = -3mA; V _I = V	_{IL} or V _{IH}	3.0	3.4		3.0		V
		V _{CC} = 4.5V; I _{OH} = -32mA; V _I = '	V _{IL} or V _{IH}	2.0	2.4		2.0		V
V _{OL}	Low-level output voltage	$V_{CC} = 4.5$ V; $I_{OL} = 64$ mA; $V_{I} = V$	_{IL} or V _{IH}		0.42	0.55		0.55	V
lı	Input leakage current	$V_{CC} = 5.5V; V_{I} = GND \text{ or } 5.5V$			±0.01	±1.0		±1.0	μA
		V _{CC} = 5.5V; V _I = 5.5V	-		0.01	1		1	μΑ
I _I	Input leakage current 74ABTH16827A	V_{CC} = 5.5V; V_{I} = V_{CC} or GND	or GND Control pins		±0.01	±1		±1	μΑ
	74ADTH10027A	$V_{CC} = 5.5V; V_I = V_{CC}$	Data pins ⁴		0.01	1		1	μA
		$V_{CC} = 5.5 V; V_{I} = 0$	Data pins		-1	-3		-5	μΑ
	Due Hald summer A familie	$V_{CC} = 4.5 V; V_{I} = 0.8 V$		35			35		μA
I _{HOLD}	Bus Hold current A inputs ⁵ 74ABTH16827A	$V_{CC} = 4.5V; V_I = 2.0V$		-75			-75		
		$V_{CC} = 5.5V; V_I = 0 \text{ to } 5.5V$		±800					
I _{OFF}	Power-off leakage current	$V_{CC} = 0.0V; V_{O} = 4.5V; V_{I} = 0V$	/ or 5.5V		±5.0	±100		±100	μΑ
I _{PU} /I _{PD}	Power-up/down 3-State output current ³	$V_{CC} = 2.1V; V_O = 0.5V; V_I = GI$ $V_{OE} = Don't care$	ND or V _{CC} ;		±5.0	±50		±50	μΑ
I _{OZH}	3-State output High current	$V_{CC} = 5.5V; V_{O} = 2.7V; V_{I} = V_{IL}$	or V _{IH}		1.0	10		10	μΑ
I _{OZL}	3-State output Low current	$V_{CC} = 5.5V; V_{O} = 0.5V; V_{I} = V_{IL}$	or V _{IH}		-1.0	-10		-10	μA
I _{CEX}	Output High leakage current	$V_{CC} = 5.5V; V_O = 5.5V; V_I = GI$	ND or V _{CC}		1.0	50		50	μA
Ι _Ο	Output current ¹	$V_{CC} = 5.5V; V_{O} = 2.5V$		-50	-70	-180	-50	-180	mA
Iссн		V_{CC} = 5.5V; Outputs High, V_{I} = V_{CC}	GND or		0.5	1		1	mA
I _{CCL}	Quiescent supply current	V_{CC} = 5.5V; Outputs Low, V_I = GND or V_{CC}			9	19		19	mA
I _{CCZ}		V_{CC} = 5.5V; Outputs 3-State; V _I = GND or V _{CC}			0.5	1		1	mA
ΔI_{CC}	Additional supply current per input pin ²	V_{CC} = 5.5V; one input at 3.4V, other inputs at V _{CC} or GND			0.2	1		1	mA

NOTES:

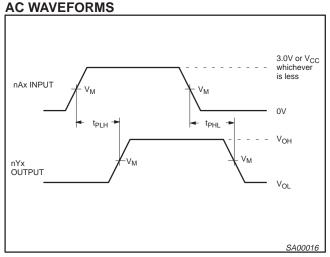
Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
This is the increase in supply current for each input at 3.4V.
This parameter is valid for any V_{CC} between 0V and 2.1V with a transition time of up to 10msec. From V_{CC} = 2.1V to V_{CC} = 5V ± 10% a transition time of up to 100µsec is permitted.
Unused pins at V_{CC} or GND.
This is the bus hold overdrive current required to force the input to the opposite logic state.

AC CHARACTERISTICS

GND = 0V, $t_R = t_F = 2.5 \text{ns}$, $C_L = 50 \text{pF}$, $R_L = 500 \Omega$

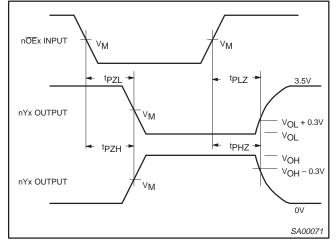
					LIMITS			
SYMBOL	PARAMETER	WAVEFORM	ſ	√ _{amb} = +25° V _{CC} = +5.0\	С /	+8	= -40 to 5°C .0V ±0.5V	UNIT
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	1	1.0 0.6	1.7 1.4	2.4 2.0	1.0 0.6	2.7 2.3	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	2	1.0 1.0	3.0 3.0	4.1 4.0	1.0 1.0	5.0 5.0	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low level	2	2.0 1.6	3.2 2.4	4.3 3.2	2.0 1.6	5.0 3.5	ns

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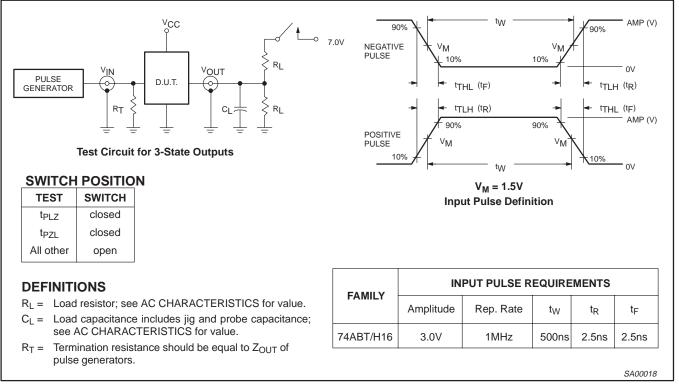


Waveform 1. Input (nAx) to Output (nYx) Propagation Delays

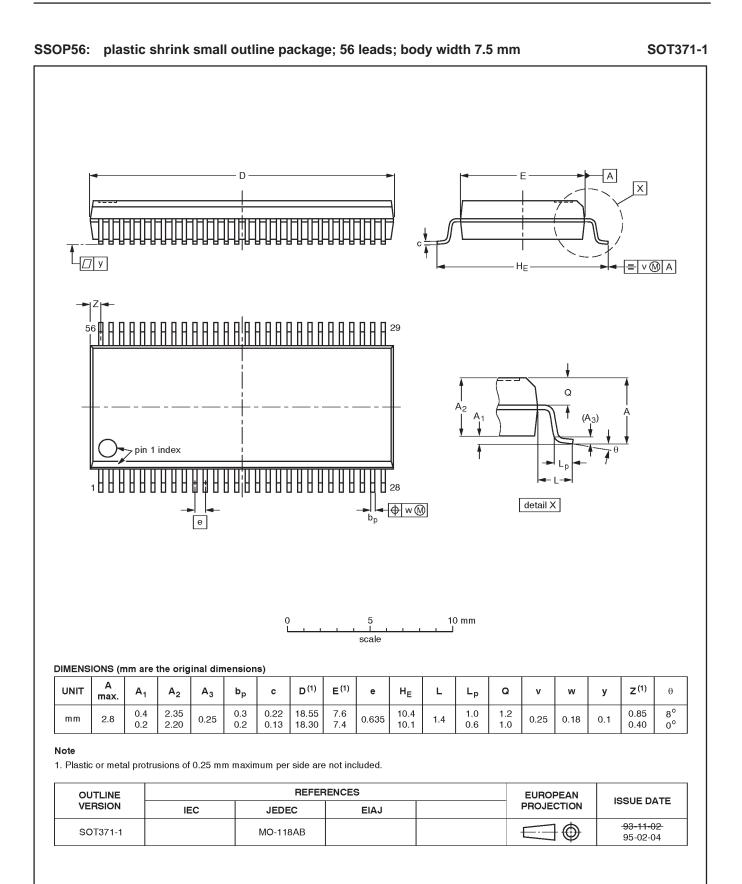
TEST CIRCUIT AND WAVEFORM



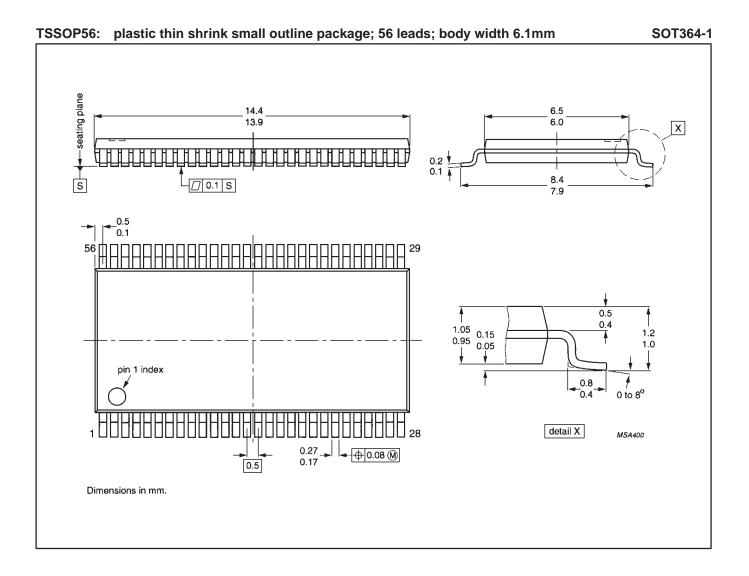
Waveform 2. 3-State Output Enable and Disable Times



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NOTES

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Data sheet status

Data sheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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